



Final Product Change Notification

202607033F01 : ATP to ATBK transfer - PCA9532BS

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 21, 2026 **Effective Date:** Nov 27, 2026

Dear PCN EBV,

Here is your personalized communication about an NXP notification.
For detailed information we invite you to [view this notification online](#)

Management summary

Changing of assembly (and test) site from ATP to ATBK for PCA9532BS.

Change Category

☐ Wafer Fab Process	☒ Assembly Process	☒ Product Marking	☐ Test Process	☐ Design
☐ Wafer Fab Materials	☒ Assembly Materials	☐ Mechanical Specification	☐ Test Equipment	☐ Errata
☐ Wafer Fab Location	☒ Assembly Location	☐ Packing/Shipping/Labeling	☒ Test Location	☐ Electrical spec./Test coverage
☐ Firmware ☐ Other				

Notification Overview

Description

-
- o Assembly plant: from ATP to ATBK
 - o Final test plant: from ATKH to ATBK (ATKH where test was previously executed will

remain a secondary option)

- o Alignment to current standard manufacturing processes, which includes;
- o Die thickness: from 250um to 280um
- o Lead frame plating material: from "Standard" NiPdAu to "Roughened" RT-NiPdAu (assures better adhesion)
- o Molding compound: from CEL-9220 to EME-G700
- o Die attach: from QMI-1234 to ADH,EN4900
- o Bond wire: from Au to Cu

Reason

Changing of assembly (and test) site from ATP to ATBK for PCA9532BS due to supplier discontinuation.

Identification of Affected Products

Top Side Marking

Assembled materials sourced from ATBK will have a different assembly site character.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jan 01, 2027

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:[view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Sep 20, 2026.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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12NC	Orderable Part Number	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New 12NC	New Orderable Part Number	New Product Type	New Product Description	Product Line	Notes	STG	Mask Set	Quality Segment
935272839118	PCA9532BS,118	PCA9532BS	PCA9532	H(V)QFN24	SOT616-1	RFS	No					BLT1				C (Non Automotive)